

MOUNTING A FLEXIBLE PRINTED CIRCUIT TO A HEAT SINK

Abstract

A method for manufacturing a printed circuit bonded to a heat sink includes adhering a conductive layer to a bond film using a first adhesive layer to produce a circuit substrate; processing the circuit substrate to produce a flexible printed circuit; and laminating the heat sink to a second surface of the bond film of the flexible printed circuit using a second adhesive layer. Another method for manufacturing a flexible printed circuit includes placing a release sheet between a first bond film and a second bond film; adhering a first conductive layer to the first bond film to produce a first circuit substrate; adhering a second conductive layer to the second bond film to produce a second circuit substrate; processing the first and the second circuit substrates each to produce a flexible printed circuit; and removing the release sheet. The method may further include laminating the flexible printed circuit to a heat sink.